

Patent Abstracts of Japan

PUBLICATION NUMBER : 53113730
PUBLICATION DATE : 04-10-78

APPLICATION DATE : 16-03-77
APPLICATION NUMBER : 52028012

APPLICANT : TOSHIBA CORP;

INVENTOR : JINNO KIYOKATSU;

INT.CL. : C23F 1/00 H01L 21/302

TITLE : METALLIC PATTERN FORMING METHOD

ABSTRACT : PURPOSE: To form a desired metallic pattern on a semiconductor substrate by removing desired parts of a tetrafluoroethylene film, by an etching process using a photoresist, formed on the substrate on which various kinds of elements have been formed and then vacuum depositing a metal.

COPYRIGHT: (C)1978,JPO&Japio

BEST AVAILABLE COPY